GL6 THRU GL10

SINGLE PHASE GLASS PASSIVATED SURFACE MOUNT FLAT BRIDGE RECTIFIER

VOLTAGE: 600 to 1000V **CURRENT: 0.8A**

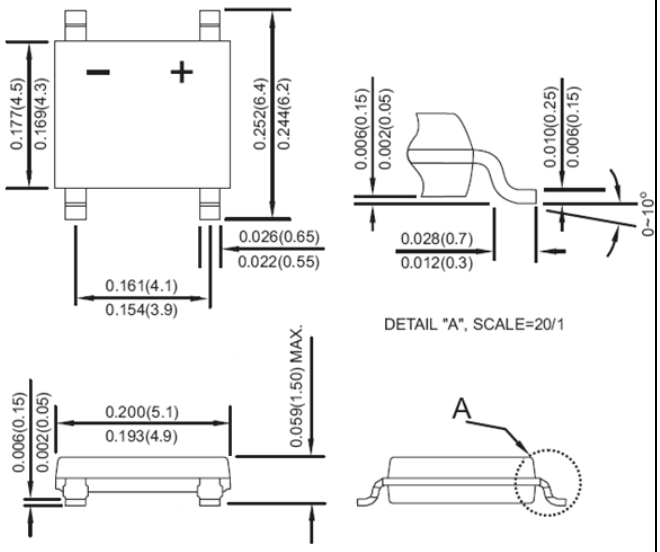
FEATURE

Ideal for printed circuit board
Glass passivated chip
Reliable low cost construction utilizing molded plastic technique
High surge current capability
Small size, simple installation
High temperature soldering guaranteed: 260℃/10 seconds

MECHANICAL DATA

Terminal: Plated leads solderable per J-STD-002
Case:UL-94 Class V-0 recognized Flame Retardant Epoxy
Polarity: Polarity symbol marked on body

LBF



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(single-phase, half -wave, 60HZ, resistive or inductive load rating at 25°C, unless otherwise stated)

	Symbol	GL6	GL8	GL10	units
Maximum Recurrent Peak Reverse Voltage	Vrrm	600	800	1000	V
Maximum RMS Voltage	Vrms	420	560	700	V
Maximum DC blocking Voltage	Vdc	600	800	1000	V
Maximum Average Forward Rectified Current on glass-epoxy P.C.B.	If(av)	0.8			A
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load	Ifsm	30			A
Maximum Instantaneous Forward Voltage at forward current 0.4A	Vf	0.95			V
Maximum DC Reverse Current Ta =25℃ at rated DC blocking voltage Ta =125℃	Ir	5.0 100.0			μA
Typical Thermal resistance junction to lead on glass-epoxy P.C.B.	Rth(jl) Rth(ja)	25 80			℃/W
Storage and Operating Junction Temperature Range	Tstg, Tj	-55 to +150			℃

Note:

RATINGS AND CHARACTERISTIC CURVES GL6 THRU GL10

FIG.1- MAXIMUM FORWARD CURRENT DERATING CURVE

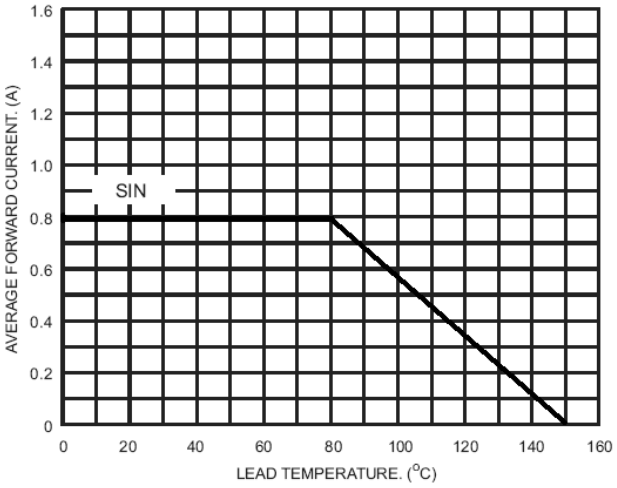


FIG.2- MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

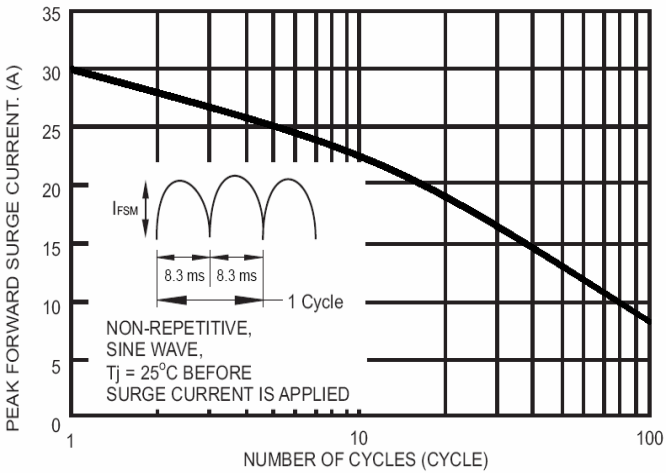


FIG.3- TYPICAL FORWARD CHARACTERISTICS

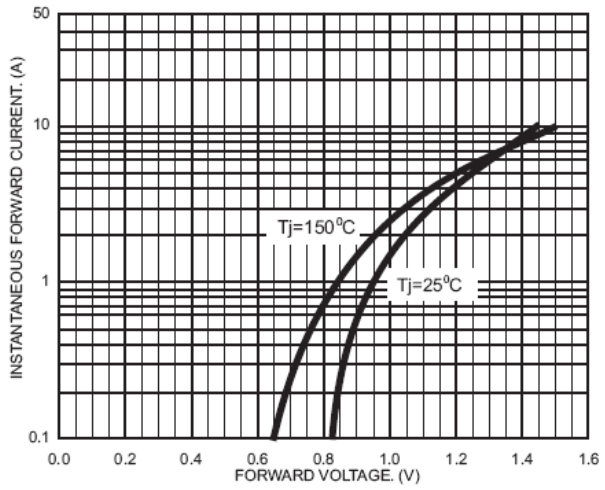


FIG.4- **TYPICAL REVERSE CHARACTERISTICS**

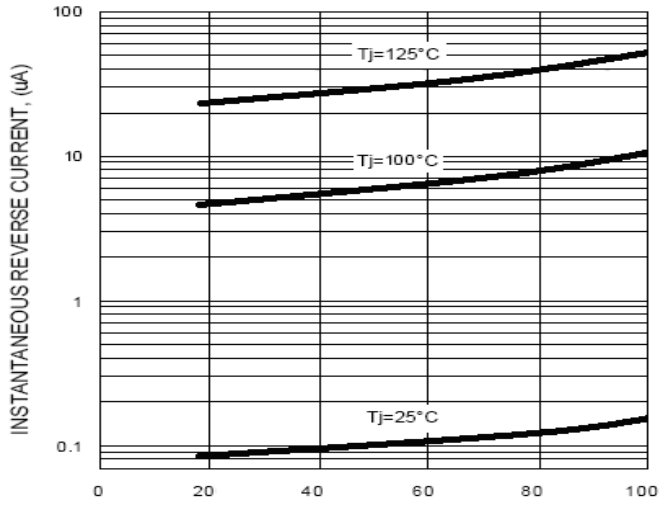


FIG.5- FORWARD POWER DISSIPATION